AD809—SPECIFICATIONS ($T_A = T_{MIN}$ to T_{MAX} , $V_S = V_{MIN}$ to V_{MAX} , $C_D = 22$ nF, unless otherwise noted)

Parameter	Condition	Min	Тур	Max	Units
TRACKING AND CAPTURE RANGE ¹	×8 Synthesis ×16 Synthesis	19.42 9.71		19.46 9.73	MHz MHz
OUTPUT JITTER	×8 Synthesis ×16 Synthesis		1.6 1.6	2.9 2.9	Degrees RMS Degrees RMS
JITTER TRANSFER Bandwidth Peaking	$C_D = 5.6 \text{ nF} (\zeta = 5)$ $C_D = 22 \text{ nF} (\zeta = 10)$		200 0.08 0.02		kHz dB dB
DUTY CYCLE TOLERANCE	×8 or ×16 Synthesis Output Jitter ≤ 2.9 Degrees RMS	15		85	%
$\begin{tabular}{lllllllllllllllllllllllllllllllllll$	 @ CLKIN/N and PECLIN/N Inputs @ TTL/CMOSIN and MUX Inputs Referenced to V_{CC} ×8 Synthesis or ×16 Synthesis 	$3.8 \\ 3.1 \\ 2.0 \\ -1.2 \\ -2.0 \\ 46 \\ $	-1.0 -1.8 52	V _{CC} 3.6 0.8 -0.7 -1.7 62	Volts Volts Volts Volts Volts Volts Volts
OUTPUT RISE/FALL TIMES 1.5 Rise Time (t_R) Fall Time (t_F)	20%-80% 80%-20%		1.1 1.1	1.5 1.5	ns ns
POWER SUPPLY VOLTAGE	V_{MIN} to V_{MAX}	4.5		5.5	Volts
POWER SUPPLY CURRENT			17	26	mA
OPERATING TEMPERATURE RANGE	T_{MIN} to T_{MAX}	-40		+85	°C

NOTES

¹Device design is guaranteed for operation over Capture Ranges and Tracking Ranges, however the device has wider capture and tracking ranges (for both ×8 and ×16 synthesis).

Specifications subject to change without notice.

ABSOLUTE MAXIMUM RATINGS*

Supply Voltage +12 V
Input Voltage (Pin 12 or Pin 13) $\dots V_{CC} + 0.6 V$
Maximum Junction Temperature
Storage Temperature Range65°C to +150°C
Lead Temperature Range (Soldering 10 sec) +300°C
ESD Rating (Human Body Model)1500 V

*Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Thermal Characteristics:

16-Pin Narrow Body SOIC Package: $\theta_{JA} = 110^{\circ}C/W$.

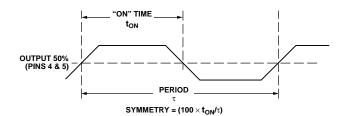


Figure 1. Symmetry

ORDERING GUIDE

Model	Temperature Range	Package Description	Package Option
AD809BR	-40°C to +85°C	16-Pin Narrow Body SOIC	R-16A
AD809BR-REEL7	-40°C to +85°C	750 Pieces, 7" Reel	R-16A

PIN DESCRIPTIONS

Pin No.	Mnemonic	Description
1	PECLINN	Differential 155 MHz Input
2	PECLIN	Differential 155 MHz Input
3	V _{CC2}	Digital V_{CC} for PECL Outputs
4	CLKOUTN	Differential 155 MHz Output
5	CLKOUT	Differential 155 MHz Output
6	V _{CC1}	Digital V_{CC} for Internal Logic
7	CF1	Loop Damping Capacitor
8	CF2	Loop Damping Capacitor
9	AV_{EE}	Analog V_{EE}
10	TTL/CMOSIN	TTL/CMOS Reference Clock Input
11	AV _{CC1}	Analog V_{CC} for PLL
12	CLKINN	PECL Differential Reference Clock Input
13	CLKIN	PECL Differential Reference Clock Input
14	AV _{CC2}	Analog V_{CC} for Input Stage
15	MUX	Input Signal Mux Control Input
16	V _{EE}	Digital V_{EE}

PIN CONFIGURATION

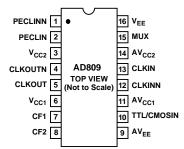


Table I.

MUX Input	Input Selected		
TTL "0"	CLKIN/CLKINN		
TTL "1"	PECLIN/PECLINN		

Table II. Applying a PECL/ECL or CMOS/TTL ReferenceInput to the AD809

Input Reference	AD809 Configuration
PECL/ECL Differential	Apply the valid PECL–level reference frequency to Pins 13 and 12. AD809 frequency synthesizer ignores the input at Pin 10.
TTL/CMOS Single-Ended	Apply the reference frequency to Pin 10.
	Connect Pins 13 and 12 to AV_{EE} (Pins 9 and 16). The AD809 senses the common-mode signal at these pins as less than valid PECL and selects the TTL/CMOS input as active.

AD809 Phase Skew

The AD809 output is in phase with the input. The falling edge at Pin 4, CLKOUTN, occurs 700 ps before the rising edge at Pin 10, TTL/CMOSIN at 27°C. The phase skew remains relatively constant over temperature. Refer to Table III for phase skew data.

Table III. Phase Skew vs. Temperature

Temperature (°C)	Skew (CLKOUTN, Pin 4, Relative to TTL/CMOSIN, Pin 10 Measured in ps at Package Pins)
-35	-1000
-20	-950
0	-850
10	-750
30	-700
50	-600
70	-450
80	-450
90	-350
100	-250

CAUTION_

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the AD809 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



DEFINITION OF TERMS

Maximum, Minimum and Typical Specifications

Specifications for every parameter are derived from statistical analyses of data taken on multiple devices from multiple wafer lots. Typical specifications are the mean of the distribution of the data for that parameter. If a parameter has a maximum (or a minimum), that value is calculated by adding to (or subtracting from) the mean six times the standard deviation of the distribution. This procedure is intended to tolerate production variations: if the mean shifts by 1.5 standard deviations, the remaining 4.5 standard deviations still provide a failure rate of only 3.4 parts per million. For all tested parameters, the test limits are guardbanded to account for tester variation to thus guarantee that no device is shipped outside of data sheet specifications.

Capture and Tracking Range

This is the range of input data rates over which the AD809 will remain in lock.

Jitter

This is the dynamic displacement of digital signal edges from their long term average positions, measured in degrees rms. Jitter on the input clock causes jitter on the synthesized clock.

Output Jitter

This is the jitter on the synthesized clock (OUTPUT, $\overline{\text{OUTPUT}}$), in degrees rms.

Jitter Transfer

The AD809 exhibits a low-pass filter response to jitter applied to its input data.

Bandwidth

This describes the frequency at which the AD809 attenuates sinusoidal input jitter by 3 dB.

Peaking

This describes the maximum jitter gain of the AD809 in dB.

Damping Factor, ζ

Damping factor, ζ describes the compensation of the second order PLL. A larger value of ζ corresponds to more damping and less peaking in the jitter transfer function.

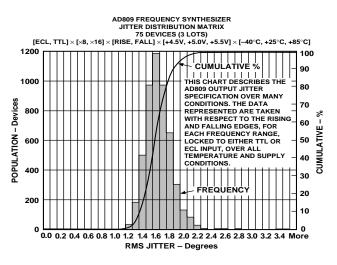
Duty Cycle Tolerance

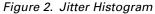
The AD809 exhibits a duty cycle tolerance that is measured by applying an input signal (nominal input frequency) with a known duty cycle imbalance and measuring the $\times 8$ or $\times 16$ output frequency.

Symmetry-Recovered Clock Duty Cycle

Symmetry is calculated as $(100 \times \text{ on time})/\text{period}$, where on time equals the time that the clock signal is greater than the midpoint between its "0" level and its "1" level.

Typical Characteristic Curves





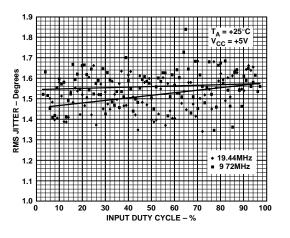


Figure 3. Jitter vs. Input Duty Cycle

V_{CC1}

USING THE AD809

Ground Planes

Use of one ground plane for connections to both analog and digital grounds is recommended.

Power Supply Connections

Use of a 10 μ F capacitor between V_{CC} and ground is recommended. Care should be taken to isolate the +5 V power trace to V_{CC2} (Pin 3). The V_{CC2} pin is used inside the device to provide the CLKOUT/CLKOUTN signals.

Use of a trace connecting Pin 14 and Pin 6 (AV_{CC2} and V_{CC1} respectively) is recommended. Use of 0.1 μ F capacitors between IC power supply and ground is recommended. Power supply decoupling should take place as close to the IC as possible. Refer to the schematic, Figure 5, for advised connections.

Transmission Lines

Use of 50 Ω transmission lines are recommended for PECL inputs.

Terminations

Termination resistors should be used for PECL input signals. Metal, thick film, 1% tolerance resistors are recommended. Termination resistors for the PECL input signals should be placed as close as possible to the PECL input pins.

Connections from the power supply to load resistors for input and output signals should be individual, not daisy chained. This will avoid crosstalk on these signals.

Loop Damping Capacitor, C_D

A ceramic capacitor may be used for the loop damping capacitor. A 22 nF capacitor provides a damping factor of 10.

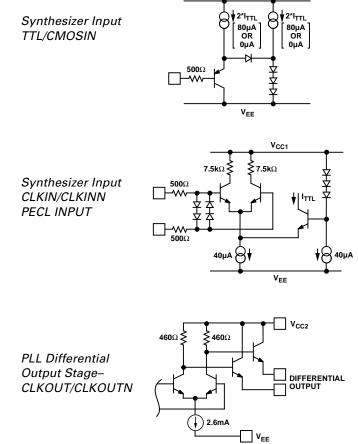


Figure 4. Simplified Schematics

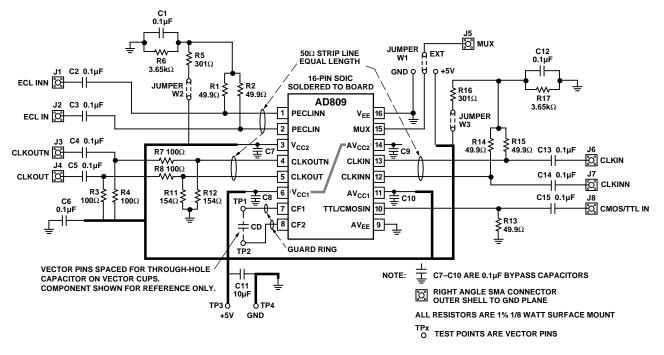


Figure 5. Evaluation Board Schematic

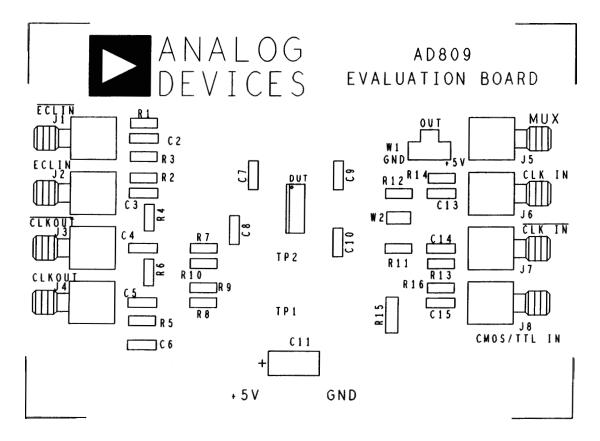


Figure 6. Evaluation Board: Component Side

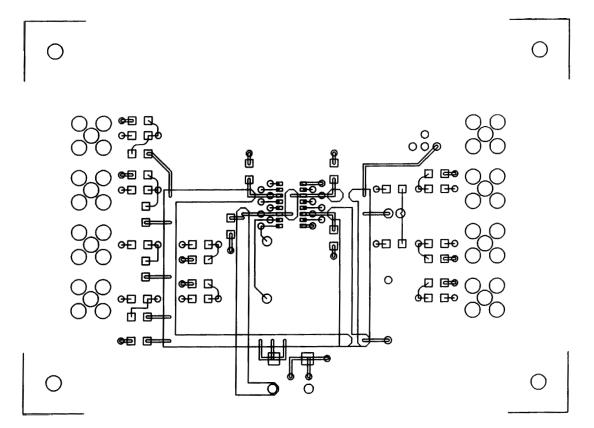


Figure 7. Evaluation Board: Solder Side

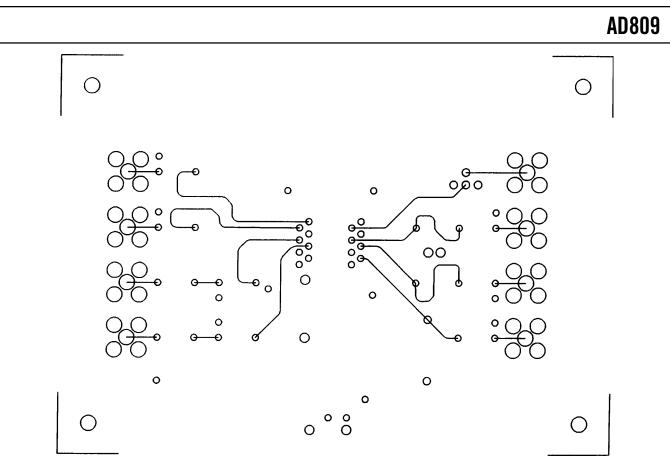


Figure 8. Evaluation Board: INT2

OUTLINE DIMENSIONS

Dimensions shown in inches and (mm).

